

APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-35℃ TO + 85℃(NOTE1)	STORAGE TEMPERATURE RANGE	-10℃ TO + 60℃(NOTE3)	
	OPERATING HUMIDITY RANGE	20 % TO 80 %(NOTE2)	STORAGE HUMIDITY RANGE	40 % TO 70 % (NOTE3)	
	VOLTAGE	AC/DC 100V	APPLICABLE CONNECTOR	DF50A-*S-1C	
	CURRENT	AWG 28 : 1.0 A AWG 30 : 0.9 A	APPLICABLE CONTACT	DF50-2830SCFA	
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	QT AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	X X
MARKING		CONFIRMED VISUALLY.			X X
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE		AC 20mV MAX 1mA (DC OR 1000 Hz).		30mΩ MAX.	X —
INSULATION RESISTANCE		100V DC.		500MΩ MIN.	X —
VOLTAGE PROOF		300V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	X —
MECHANICAL CHARACTERISTICS					
MECHANICAL OPERATION		30TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: 50mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS. ① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X —
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 10 CYCLE FOR EACH, FOR 3 DIRECTIONS.			
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.		① CONTACT RESISTANCE: 50mΩ MAX. ② INSULATION RESISTANCE: 100MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X —
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55→+85℃ TIME 30→ 30min. UNDER 5 CYCLES. THE TRANSFERRING TIME OF THE TANK IS 2~3 min.			
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△					
			APPROVED	KI. AKIYAMA	12. 06. 26
			CHECKED	HK. UMEHARA	12. 06. 26
			DESIGNED	ST. SATO	12. 06. 26
			DRAWN	ST. SATO	12. 06. 26
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-346572-01
HRS	SPECIFICATION SHEET		PART NO.	DF50A-*P-1H(51)	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL665-	△ 1/2

SPECIFICATIONS				
ITEM	TEST METHOD	REQUIREMENTS	QT	AT
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 245°C FOR INSERTION DURATION, 5 sec.	SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	X	—
RESISTANCE TO SOLDERING HEAT	1) REFLOW SOLDERING «REFLOW AREA» MAX250°C WITHIN 10 sec MIN 220°C WITHIN 60 sec 《PREHEATING AREA》 150~180°C 90~120s 2) MANUAL SOLDERING SOLDERING IPON TEMPERRATURE 350±10°C SOLDERING TIME 3~4s. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	—
REMARKS				
NOTE 1: INCLUDING THE TEMPERATURE RISE BY CURRENT.				
NOTE 2: NON-CONDENSING				
NOTE 3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD.				
AFTER PCB BOARD,OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION				
Unless otherwise specifid , refer to JIS C 5402.				
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